

Excellent Integrated System Limited

Stocking Distributor

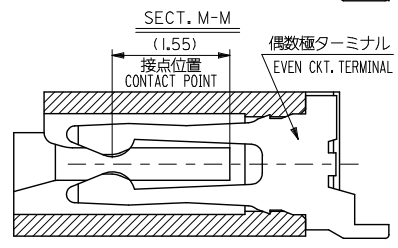
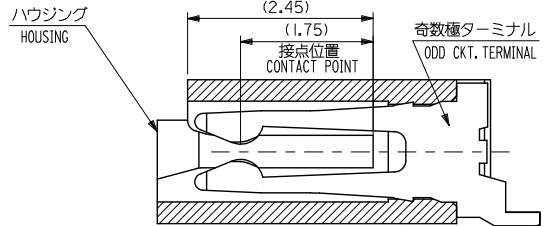
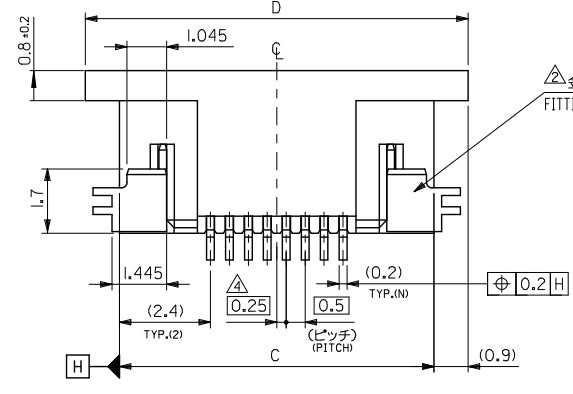
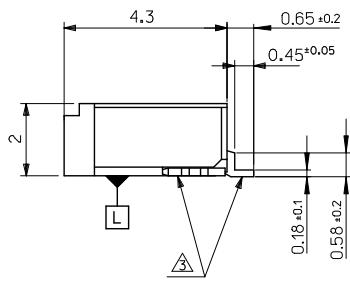
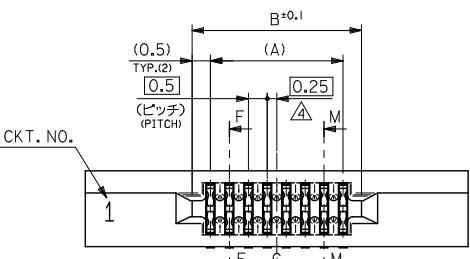
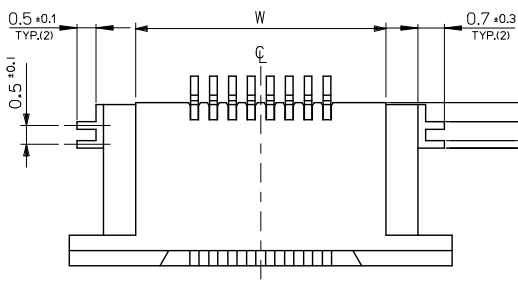
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[0526891687](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

10 9 8 7 6 5 4 3 2 1



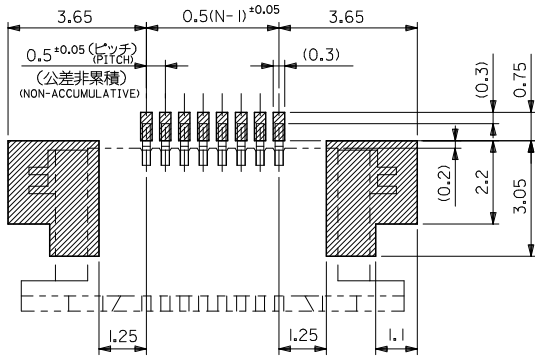
注記(NOTES)

- 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅 PHOSPHOR BRONZE ± 0.2
銅ヒスマスマスチック 1.0 マイクロメートル以上 TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1.0 マイクロメートル以上 NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46 ナイロン (46NYLON), UL94V-0
金具 (FITTING NAIL): リン青銅 PHOSPHOR BRONZE ± 0.2
銅メッキ 1.0 マイクロメートル以上 TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1.0 マイクロメートル以上 NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM
- パターン剥離止め用金具。FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN) ソルダテール半田付け面のスレ量、及び金具半田付け面のスレ量は、基準面 L に対し上方向 0.1MAX、下方向 0.15MAX、とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX, LOWER DIRECTION 0.15MAX.
偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
- 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

REVISED EC NO. J2016-1029 DRAWN: SKITAZAWA 2016/03/30 CHKD: APPR: IKUSIHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL NO.
	0.25 UNDER	UNDER	±0.03	MM ONLY	---	METRIC	52689-***49
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	TITLE	
	0.5 OVER	1.0 UNDER	±0.1	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-	
1.0 OVER	10 UNDER	±0.2	CHECKED BY	DATE			
10 OVER	30 UNDER	±0.25	K. TOJO	'04/02/03			
30 OVER		±0.3	APPROVED BY	DATE			
ANGULAR	±3 °		M. SASAO	'04/02/03			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	SEE SHEET 2	DOCUMENT NO.		
			A3		SD-52689-034		SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

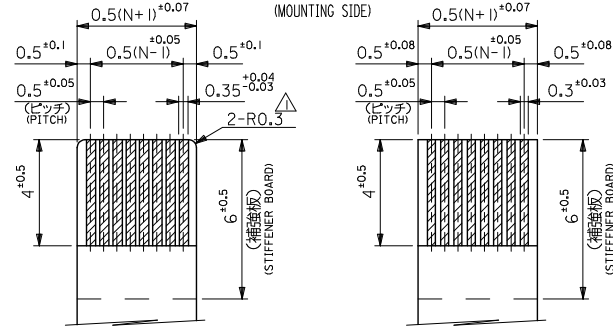
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合 F.P.C. 推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3+0.03)
(THICKNESS: 0.3+0.03)

適合 F.F.C. 推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3+0.03)
(THICKNESS: 0.3+0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R.O. 3は、FPCの導体側にかからないこと。
R.O.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

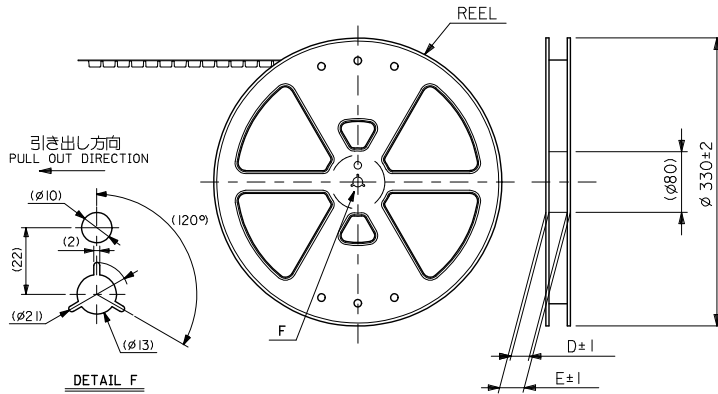
17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	極数 CKT.
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REVISED EC NO. J2016-1029 DRAWN: SKITAZAWA 2016/03/30 CHKD: APPR: IKUSIHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	'04/02/03	0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
	1.0 OVER	10 UNDER	±0.2	K. TOJO	'04/02/03	DOCUMENT NO. SD-52689-034		
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	SHEET NO. 2 OF 2			
30 OVER		±0.3	M. SASAO	'04/02/03	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR	±3 °		SEE TABLE					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3					

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

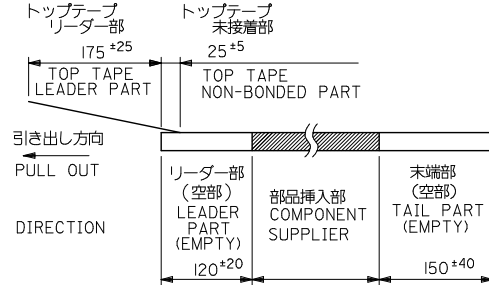


注記 NOTES

1. 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION, SEE SD-52689-034.

2. 梱包数量：1000個/リール
NUMBER OF CONNECTORS: 1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)

0.1~1.3N {10~130gf}

尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

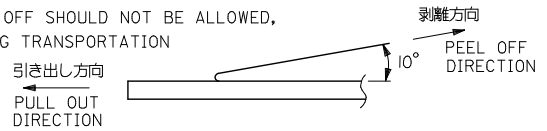
PEELING OFF FORCE OF TOP TAPE

0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)

THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT

PEEL OFF SHOULD NOT BE ALLOWED,

DURING TRANSPORTATION



5. 材料 キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE: POLYPROPYLENE
TOP TAPE: PET, PE, PEF
REEL: POLYSTYRENE (PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は52689-**-93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-**-93.

7. FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォーム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

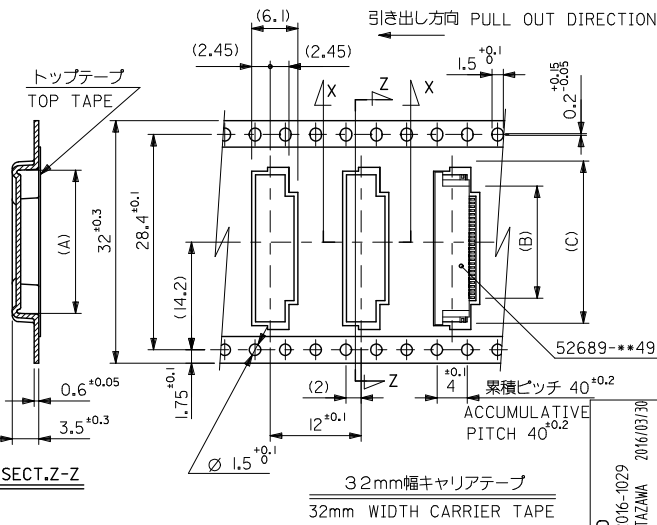
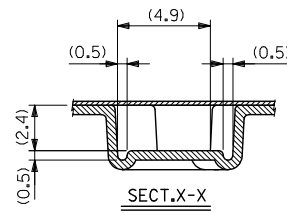
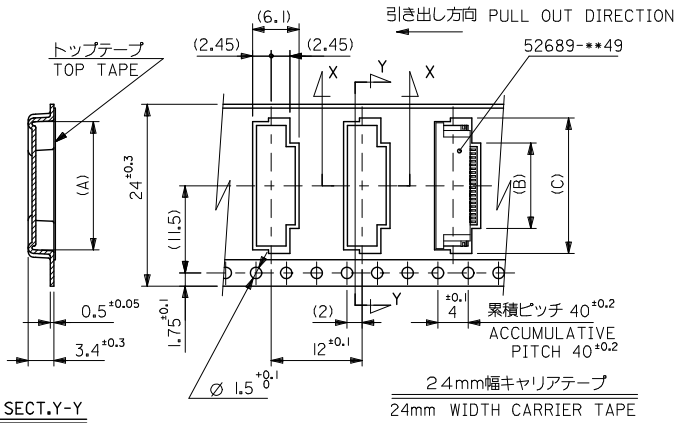
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

8. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED EC NO: J2016-1029 DRAWN: SKITAZAWA 2016/03/30 CHKD: APPR: IKUSHIARA01 2016/04/15 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	(UNLESS SPECIFIED)		MM ONLY		---	METRIC	
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE	
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE		
1.0 OVER	10 UNDER	±0.2	K. TOJO	2004/02/03			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE			
30 OVER		±0.3	M. SASAO	2004/02/03			
ANGULAR	±3		MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE	SEE SHEET 2,3		SD-52689-035	1 OF 3	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

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10 9 8 7 6 5 4 3 2 1



32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30
24	29.4	25.4	17.4	10.8	16.4	-2087	20
			16.4	9.8	15.4	-1887	18
			15.4	8.8	14.4	-1687	16
			14.9	8.3	13.9	-1587	15
			12.4	5.8	11.4	-1087	10
			11.4	4.8	10.4	-0887	8
			10.9	4.3	9.9	-0787	7
9.9	3.3	8.9	52689 -0587	5			

52689-***87

MODEL NO. キャリアテープ幅 CARRIER TAPE WIDTH

E	D	(B)	(A)	MATERIAL NO.	部品コード PART NO.
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REVISED EC NO. J2016-1029 DRAWN:SKITAZAWA 2016/03/30 CHKD: APPR:IKUSIHARA01 2016/04/15	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	MM ONLY	---	METRIC	
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	TITLE	
	0.5 OVER	1.0 UNDER	±0.1	H.KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-	
	1.0 OVER	10 UNDER	±0.2	CHECKED BY	DATE		
10 OVER	30 UNDER	±0.3	X.TOJO	2004/02/03			
30 OVER			APPROVED BY	DATE			
	ANGULAR	±3	M.SASAO	2004/02/03	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
			SEE TABLE		SD-52689-035		2 OF 3
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2 1

